

Final datasheet

XHP™2 module with CoolSiC™ Trench MOSFET and NTC

Features

- · Electrical features
 - $V_{DSS} = 2300 V$
 - $I_{DN} = 1500 \text{ A} / I_{DRM} = 3000 \text{ A}$
 - High current density
 - Low inductive design
 - Low switching losses
 - $T_{vj,op} = 175$ °C
- Mechanical features
 - Substrate for low thermal resistance
 - Copper base plate
 - High creepage and clearance distances
 - High power density
 - Package with CTI > 600

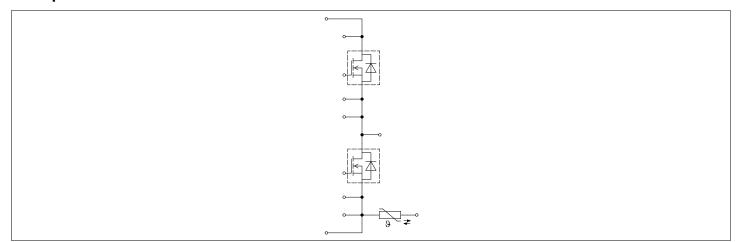
Potential applications

- Central inverter
- Wind power generation
- · Energy storage systems
- Industrial drives
- Traction drives
- DC/DC converter
- High-power converters
- High-frequency switching application

Product validation

• Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description





XHP™2 module

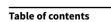




Table of contents

| | Description | 1 |
|---|------------------------------|---|
| | Features | 1 |
| | Potential applications | 1 |
| | Product validation | 1 |
| | Table of contents | 2 |
| 1 | Package | 3 |
| 2 | MOSFET Inverter | 3 |
| 3 | Body diode (MOSFET Inverter) | 5 |
| 4 | NTC-Thermistor | 6 |
| 5 | Characteristics diagrams | 7 |
| 6 | Circuit diagram | 3 |
| 7 | Package outlines | 4 |
| 8 | Module label code | 5 |
| | Revision history 1 | 6 |
| | Disclaimer | 7 |

XHP™2 module

1 Package



1 Package

Table 1 Insulation coordination

| Parameter | Symbol | Note or test condition | Values | Unit |
|------------------------------|-------------------|---------------------------|--------|------|
| Isolation test voltage | V _{ISOL} | RMS, f = 50 Hz, t = 1 min | 4.0 | kV |
| Material of module baseplate | | | Cu | |
| Comparative tracking index | СТІ | | > 600 | |

Table 2 Characteristic values

| Parameter | Symbol | Note or test condition | | | Values | | Unit |
|--|----------------------|--|-----------|------|--------|------|------|
| | | | | Min. | Тур. | Max. | |
| Stray inductance module | L _{sCE} | | | | 10 | | nH |
| Module lead resistance, terminals - chip | R _{CC'+EE'} | T_C = 25 °C, per switch | | | 0.4 | | mΩ |
| Storage temperature | $T_{\rm stg}$ | | | -40 | | 150 | °C |
| Maximum baseplate operation temperature | T_{BPmax} | | | | | 150 | °C |
| Mounting torque for module mounting | М | - Mounting according to valid application note | M6, Screw | 3 | | 6 | Nm |
| Terminal connection | М | - Mounting according to | M3, Screw | 0.9 | | 1.1 | Nm |
| torque | | valid application note | M8, Screw | 8 | | 10 | |
| Weight | G | | • | | 1020 | | g |

2 MOSFET Inverter

Table 3 Maximum rated values

| Parameter | Symbol | Note or test condition | | Values | Unit |
|---|------------------|--|----------------------------|--------|------|
| Drain-source voltage | V _{DSS} | | T _{vj} = 25 °C | 2300 | V |
| Implemented drain current | I _{DN} | | | 1500 | А |
| Continuous DC drain current | I _{DDC} | $T_{\rm vj}$ = 175 °C, $V_{\rm GS}$ = 15 V | T _C = 65 °C | 1070 | А |
| Repetitive peak drain current | I _{DRM} | verified by design, t _p lim | ited by T _{vjmax} | 3000 | А |
| Gate-source voltage, max. transient voltage | V _{GS} | D < 0.01 | | -10/23 | V |
| Gate-source voltage, max. static voltage | V _{GS} | | | -7/20 | V |

XHP™2 module

2 MOSFET Inverter



Table 4 Recommended values

| Parameter | Symbol | Note or test condition | Values | Unit |
|------------------------|----------------------|------------------------|--------|------|
| On-state gate voltage | V _{GS(on)} | | 1518 | V |
| Off-state gate voltage | V _{GS(off)} | | -5 | V |

Table 5 Characteristic values

| Parameter | Symbol | Note or test condition | | | Values | | Unit |
|--------------------------------|---------------------|--|--|------|--------|------|------|
| | | | | Min. | Тур. | Max. | 1 |
| Drain-source on-resistance | R _{DS(on)} | I _D = 1500 A | $V_{\rm GS} = 15 \text{ V},$ $T_{\rm vj} = 25 ^{\circ}\text{C}$ | | 1.27 | 1.59 | mΩ |
| | | | V _{GS} = 15 V, T _{vj} = 125 °C | | 2.27 | 2.84 | |
| | | | V _{GS} = 15 V, T _{vj} = 175 °C | | 3.07 | 3.84 | |
| Gate threshold voltage | V _{GS(th)} | I_D = 675 mA, V_{DS} = V_{GS} , T_{vj} after 1ms pulse at V_{GS} = + | | 3.45 | 4.2 | 5.15 | V |
| Total gate charge | Q _G | $V_{\rm DD}$ = 1500 V, $V_{\rm GS}$ = -5/15 V | /, T _{vj} = 25 °C | | 3.98 | | μC |
| Internal gate resistor | R _{Gint} | T _{vj} = 25 °C | | | 1.5 | | Ω |
| Input capacitance | C _{ISS} | $f = 100 \text{ kHz}, V_{DS} = 1500 \text{ V},$ $V_{GS} = 0 \text{ V}$ | T _{vj} = 25 °C | | 143 | | nF |
| Output capacitance | C _{OSS} | $f = 100 \text{ kHz}, V_{DS} = 1500 \text{ V},$ $V_{GS} = 0 \text{ V}$ | T _{vj} = 25 °C | | 3.08 | | nF |
| Reverse transfer capacitance | C _{rss} | $f = 100 \text{ kHz}, V_{DS} = 1500 \text{ V},$ $V_{GS} = 0 \text{ V}$ | T _{vj} = 25 °C | | 0.15 | | nF |
| C _{OSS} stored energy | E _{OSS} | $V_{\rm DS}$ = 1500 V, $V_{\rm GS}$ = -5/15 V | , T _{vj} = 25 °C | | 4.35 | | mJ |
| Drain-source leakage current | I _{DSS} | $V_{\rm DS}$ = 2300 V, $V_{\rm GS}$ = -5 V | T _{vj} = 25 °C | | | 786 | μA |
| Gate-source leakage current | I _{GSS} | $V_{\rm DS}$ = 0 V, $T_{\rm vj}$ = 25 °C | V _{GS} = 20 V | | | 2400 | nA |
| Turn-on delay time | t _{d on} | $I_{\rm D} = 1500 \text{A}, R_{\rm Gon} = 0.1 \Omega,$ | T _{vj} = 25 °C | | 210 | | ns |
| (inductive load) | | $V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V},$ | T _{vj} = 125 °C | | 200 | | |
| | | $t_{\text{dead}} = 3000 \text{ ns}, 0.1 \text{ V}_{\text{GS}}$ to 0.1 I _D | T _{vj} = 175 °C | | 200 | | |
| Rise time (inductive load) | t _r | $I_{\rm D} = 1500 \text{A}, R_{\rm Gon} = 0.1 \Omega,$ | T _{vj} = 25 °C | | 95 | | ns |
| | | $V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V},$ | T _{vj} = 125 °C | | 95 | | |
| | | $t_{\text{dead}} = 3000 \text{ ns}, 0.1 \text{ I}_{\text{D}} \text{ to}$ 0.9 I _D | T _{vj} = 175 °C | | 100 | | |

(table continues...)

XHP™2 module

3 Body diode (MOSFET Inverter)



Table 5 (continued) Characteristic values

| Parameter | Symbol | Note or test condition | | | Values | | Unit |
|--|--------------------|--|---|--------|--------|------|------|
| | | | | Min. | Тур. | Max. | |
| Turn-off delay time | $t_{\sf doff}$ | $I_{\rm D}$ = 1500 A, $R_{\rm Goff}$ = 1.4 Ω , | T _{vj} = 25 °C | | 380 | | ns |
| (inductive load) | | $V_{DD} = 1500 \text{ V},$ $V_{GS} = -5/15 \text{ V}, 0.9 \text{ V}_{GS} \text{ to}$ | T _{vj} = 125 °C | | 420 | | |
| | | 0.9 I _D | T _{vj} = 175 °C | | 445 | | |
| Fall time (inductive load) | t _f | $I_{\rm D}$ = 1500 A, $R_{\rm Goff}$ = 1.4 Ω , | T _{vj} = 25 °C | | 85 | | ns |
| | | ′ - 1500 V | T _{vj} = 125 °C | | 115 | | |
| | | I _D | T _{vj} = 175 °C | | 135 | | |
| Turn-on time (resistive load) | t _{on_R} | $I_{\rm D} = 500 \text{ A}, V_{\rm DD} = 1500 \text{ V},$ $V_{\rm GS} = -5/15 \text{ V},$ $R_{\rm Gon} = 0.1 \Omega$ | T _{vj} = 25 °C | 605.00 | | | ns |
| Turn-on energy loss per | E _{on} | $I_{\rm D}$ = 1500 A, $V_{\rm DD}$ = 1500 V, | T _{vj} = 25 °C | | 305 | | mJ |
| pulse | | $L_{\sigma} = 14 \text{ nH}, V_{GS} = -5/15 \text{ V},$ $R_{Gon} = 0.1 \Omega, \text{ di/dt} =$ | T _{vj} = 125 °C | | 390 | | |
| | | 12.7 kA/ μ s ($T_{vj} = 175$ °C), $t_{dead} = 3000 \text{ ns}$ | T _{vj} = 175 °C | | 470 | | |
| Turn-on energy loss per | E _{on,o} | $I_{\rm D}$ = 1500 A, $V_{\rm DD}$ = 1500 V, | T _{vj} = 25 °C | | 300 | | mJ |
| pulse, optimized | | $L_{\sigma} = 14 \text{ nH}, V_{GS} = -5/15 \text{ V},$ $R_{Gon,o} = 0.1 \Omega, \text{ di/dt} =$ | T _{vj} = 125 °C | | 305 | | |
| | | 13 kA/ μ s (T _{vj} = 175 °C), t_{dead} = 500 ns | T _{vj} = 175 °C | | 330 | | |
| Turn-off energy loss per | $E_{\rm off}$ | $I_{\rm D}$ = 1500 A, $V_{\rm DD}$ = 1500 V, | T _{vj} = 25 °C | | 220 | | mJ |
| pulse | | $L_{\sigma} = 14 \text{ nH}, V_{GS} = -5/15 \text{ V},$ $R_{Goff} = 1.4 \Omega, \text{ dv/dt} = 11$ | T _{vj} = 125 °C | | 250 | | |
| | | $kV/\mu s (T_{vj} = 175 °C)$ | T _{vj} = 175 °C | | 270 | | |
| SC data | I _{SC} | $V_{GS} = -5/15 \text{ V},$ $V_{DD} = 1500 \text{ V}, V_{DSmax} = V_{DSS} - L_{SDS} * \text{di/dt}$ | $t_{\rm P} \le 3 \mu{\rm s},$ $T_{\rm vj} = 175 {}^{\circ}{\rm C}$ | | 9000 | | A |
| Thermal resistance, junction to case | R_{thJC} | per MOSFET | | | | 25.1 | K/kW |
| Thermal resistance, case to heat sink | R_{thCH} | per MOSFET, λ _{grease} = 5 W/ | /(m*K) | | 4.95 | | K/kW |
| Temperature under switching conditions | T _{vj op} | | | -40 | | 175 | °C |

3 Body diode (MOSFET Inverter)

Table 6 Maximum rated values

| Parameter | Symbol | Note or test condition | | Values | Unit |
|-------------------------------|-----------------|---|------------------------|--------|------|
| DC body diode forward current | I _{SD} | $T_{\rm vj} = 175 {\rm ^{\circ}C}, V_{\rm GS} = -5 {\rm V}$ | T _C = 65 °C | 970 | A |

XHP™2 module

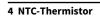




Table 6 (continued) Maximum rated values

| Parameter | Symbol | Note or test condition | | Values | Unit |
|--------------------------|------------------|--|--------------------------|--------|-------------------|
| I ² t - value | I ² t | $V_{\rm DS} = 0 \text{ V}, V_{\rm GS} = -5 \text{ V},$ | T _{vj} = 125 °C | 340 | kA ² s |
| | | $t_{\rm P} = 10 \; {\rm ms}$ | T _{vj} = 175 °C | 280 | |

Table 7 Characteristic values

| Parameter | Symbol | Note or test condition | | | Values | | Unit |
|--------------------------|--------------------|--|--------------------------|------|--------|------|------|
| | | | | Min. | Тур. | Max. | |
| Forward voltage | $V_{\rm SD}$ | $I_{SD} = 1500 \text{ A}, V_{GS} = -5 \text{ V}$ | T _{vj} = 25 °C | | 5 | 6.25 | V |
| | | | T _{vj} = 125 °C | | 4.4 | 5.5 | |
| | | | T _{vj} = 175 °C | | 4.2 | 5.25 | |
| Reverse recovery energy | $E_{\rm rec}$ | $I_{SD} = 1500 \text{ A, di}_{s}/\text{dt} =$ | T _{vj} = 25 °C | | 4.35 | | mJ |
| | | 12.7 kA/ μ s (T _{vj} = 175 °C), V_{DD} = 1500 V, | T _{vj} = 125 °C | | 31 | | |
| | | $V_{GS} = -5/15 \text{ V},$ $t_{dead} = 3000 \text{ ns}$ | T _{vj} = 175 °C | | 47 | | |
| Reverse recovery energy, | E _{rec,o} | $I_{SD} = 1500 \text{ A, di}_{s}/\text{dt} =$ | T _{vj} = 25 °C | | 4.35 | | mJ |
| optimized | | 13 kA/ μ s (T _{vj} = 175 °C), V_{DD} = 1500 V, | T _{vj} = 125 °C | | 7.5 | | |
| | | $V_{GS} = -5/15 \text{ V},$ $t_{dead} = 500 \text{ ns}$ | T _{vj} = 175 °C | | 13 | | 1 |

4 NTC-Thermistor

Table 8 Characteristic values

| Parameter | Symbol | Note or test condition | | Values | | Unit |
|-------------------------------|---------------------|--|------|--------|------|------|
| | | | Min. | Тур. | Max. | |
| Rated resistance | R ₂₅ | T _{NTC} = 25 °C | | 5 | | kΩ |
| Deviation of R ₁₀₀ | ∆R/R | $T_{\rm NTC} = 100 {}^{\circ}{\rm C}$, $R_{100} = 493 \Omega$ | -5 | | 5 | % |
| Power dissipation | P ₂₅ | T _{NTC} = 25 °C | | | 20 | mW |
| B-value | B _{25/50} | $R_2 = R_{25} \exp[B_{25/50}(1/T_2-1/(298,15 \text{ K}))]$ | | 3375 | | К |
| B-value | B _{25/80} | $R_2 = R_{25} \exp[B_{25/80}(1/T_2-1/(298,15 \text{ K}))]$ | | 3411 | | K |
| B-value | B _{25/100} | $R_2 = R_{25} \exp[B_{25/100}(1/T_2-1/(298,15 \text{ K}))]$ | | 3433 | | K |

Note: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4

5 Characteristics diagrams

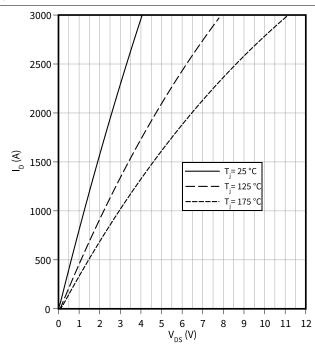


5 Characteristics diagrams

Output characteristic (typical), MOSFET Inverter

 $I_D = f(V_{DS})$

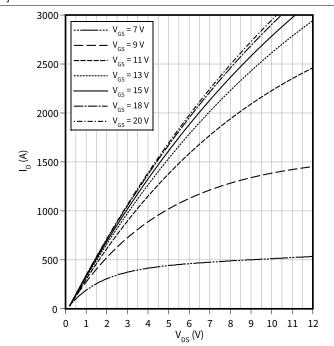
 $V_{GS} = 15 V$



Output characteristic field (typical), MOSFET Inverter

 $I_D = f(V_{DS})$

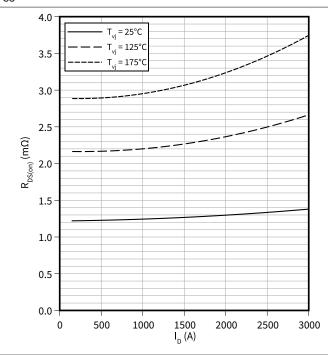
T_{vj} = 175 °C



Drain source on-resistance (typical), MOSFET Inverter

 $R_{DS(on)} = f(I_D)$

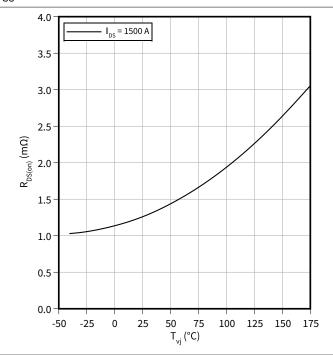
 $V_{GS} = 15 V$



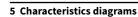
Drain source on-resistance (typical), MOSFET Inverter

 $R_{\mathsf{DS}(\mathsf{on})} = \mathsf{f}(\mathsf{T}_{\mathsf{v}\mathsf{j}})$

 $V_{GS} = 15 V$



XHP™2 module

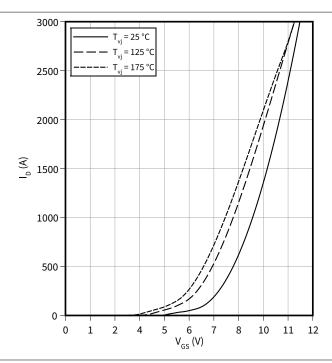




Transfer characteristic (typical), MOSFET Inverter

$$I_D = f(V_{GS})$$

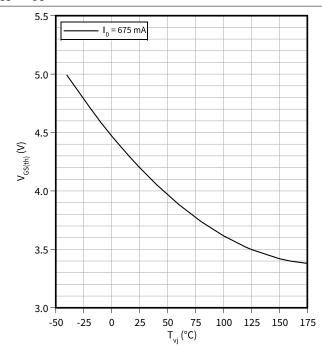
$$V_{DS} = 20 V$$



Gate-source threshold voltage (typical), MOSFET Inverter

$$V_{GS(th)} = f(T_{vj})$$

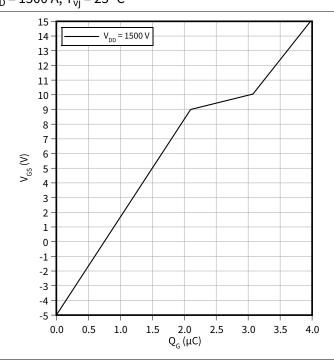
$$V_{GS} = V_{DS}$$



Gate charge characteristic (typical), MOSFET Inverter

$$V_{GS} = f(Q_G)$$

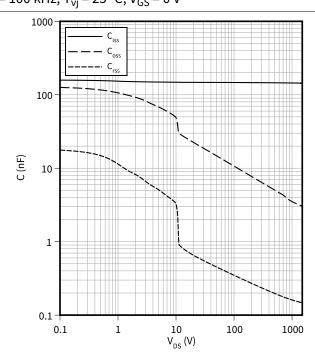
$$I_D = 1500 \text{ A}, T_{vj} = 25 \,^{\circ}\text{C}$$



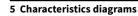
Capacity characteristic (typical), MOSFET Inverter

$$C = f(V_{DS})$$

$$f = 100 \text{ kHz}, T_{vj} = 25 \text{ °C}, V_{GS} = 0 \text{ V}$$



XHP™2 module

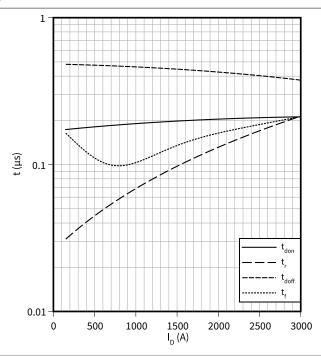




Switching times (typical), MOSFET Inverter

 $t = f(I_D)$

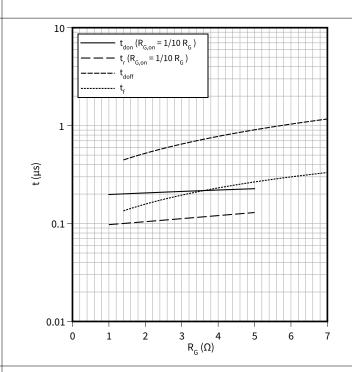
 R_{Goff} = 1.4 Ω , R_{Gon} = 0.1 Ω , V_{DD} = 1500 V, T_{vj} = 175 °C, V_{GS} = -5/15 V



Switching times (typical), MOSFET Inverter

 $t = f(R_G)$

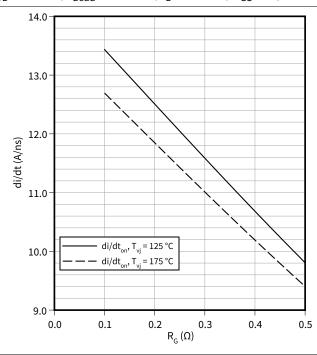
 V_{DD} = 1500 V, I_{D} = 1500 A, T_{vj} = 175 °C, V_{GS} = -5/15 V



Current slope (typical), MOSFET Inverter

 $di/dt = f(R_G)$

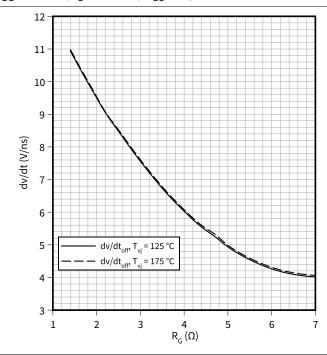
 V_{DD} = 1500 V, t_{dead} = 3000 ns, I_{D} = 1500 A, V_{GS} = -5/15 V



Voltage slope (typical), MOSFET Inverter

 $dv/dt = f(R_G)$

 $V_{DD} = 1500 \text{ V}, I_D = 1500 \text{ A}, V_{GS} = -5/15 \text{ V}$



XHP™2 module

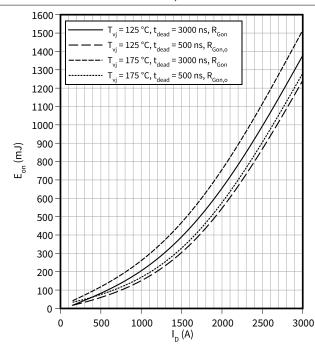
5 Characteristics diagrams



Switching losses (typical), MOSFET Inverter

$$E_{on} = f(I_D)$$

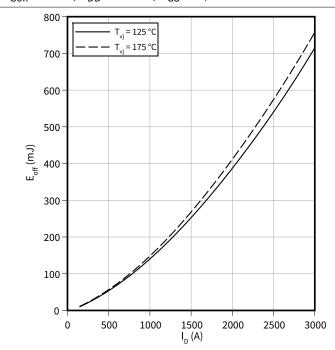
$$V_{DD} = 1500 \text{ V}, R_{Gon} = 0.1 \Omega, R_{Gon,o} = 0.1 \Omega, V_{GS} = -5/15 \text{ V}$$



Switching losses (typical), MOSFET Inverter

$$E_{off} = f(I_D)$$

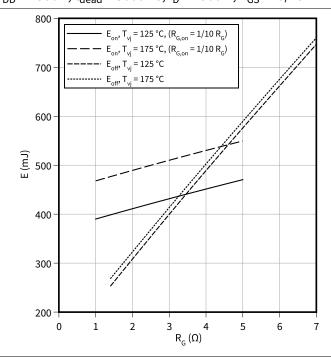
$$R_{Goff}$$
 = 1.4 Ω , V_{DD} = 1500 V, V_{GS} = -5/15 V



Switching losses (typical), MOSFET Inverter

 $E = f(R_G)$

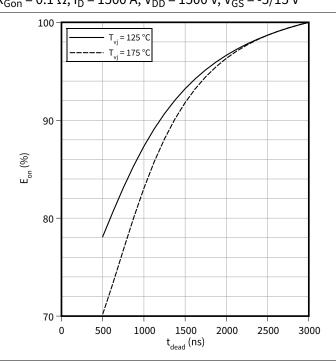
$$V_{DD} = 1500 \text{ V}, t_{dead} = 3000 \text{ ns}, I_D = 1500 \text{ A}, V_{GS} = -5/15 \text{ V}$$



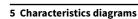
Switching losses (typical), MOSFET Inverter

$$E_{on} = f(t_{dead})$$

$$R_{Gon} = 0.1 \Omega$$
, $I_D = 1500 A$, $V_{DD} = 1500 V$, $V_{GS} = -5/15 V$



XHP™2 module

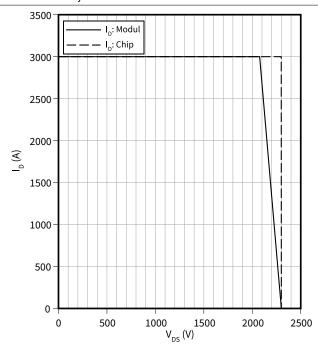




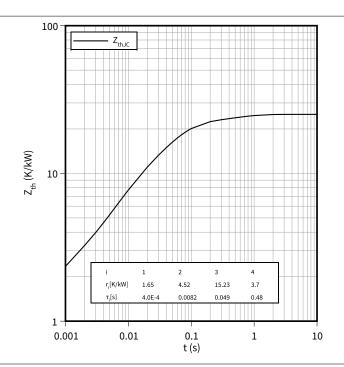
Reverse bias safe operating area (RBSOA), MOSFET Inverter

 $I_D = f(V_{DS})$

$$R_{Goff} = 1.4 \Omega$$
, $T_{vi} = 175 \,^{\circ}$ C, $V_{GS} = -5/15 \,^{\circ}$ V



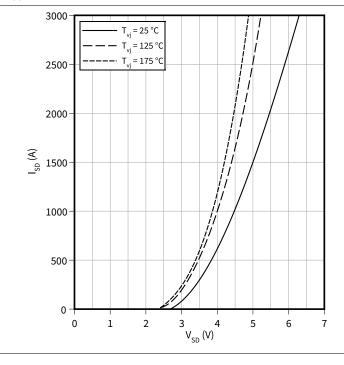
Transient thermal impedance, MOSFET Inverter $Z_{th} = f(t)$



Forward characteristic body diode (typical), MOSFET Inverter

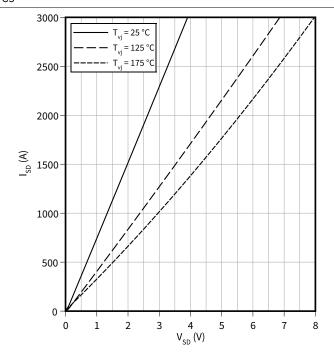
 $I_{SD} = f(V_{SD})$

$$V_{GS} = -5 V$$



Forward characteristic body diode (typical), MOSFET Inverter

 $I_{SD} = f(V_{SD})$



XHP™2 module

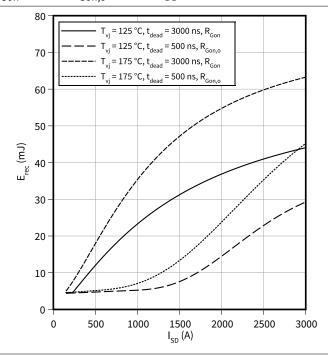
5 Characteristics diagrams



Switching losses body diode (typical), MOSFET Inverter

 $E_{rec} = f(I_{SD})$

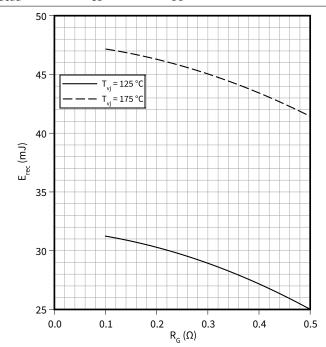
 $R_{Gon} = 0.1 \Omega$, $R_{Gon,o} = 0.1 \Omega$, $V_{DD} = 1500 V$



Switching losses body diode (typical), MOSFET Inverter

 $E_{rec} = f(R_G)$

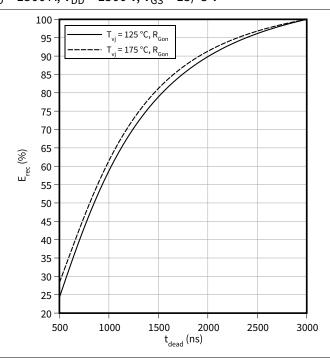
 t_{dead} = 3000 ns, I_{SD} = 1500 A, V_{DD} = 1500 V



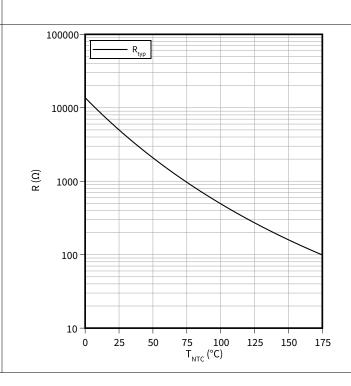
Switching losses body diode (typical), MOSFET Inverter

 $E_{rec} = f(t_{dead})$

 $I_D = 1500 \text{ A}, V_{DD} = 1500 \text{ V}, V_{GS} = 15/-5 \text{ V}$



Temperature characteristic (typical), NTC-Thermistor $R = f(T_{NTC})$



6 Circuit diagram



6 Circuit diagram

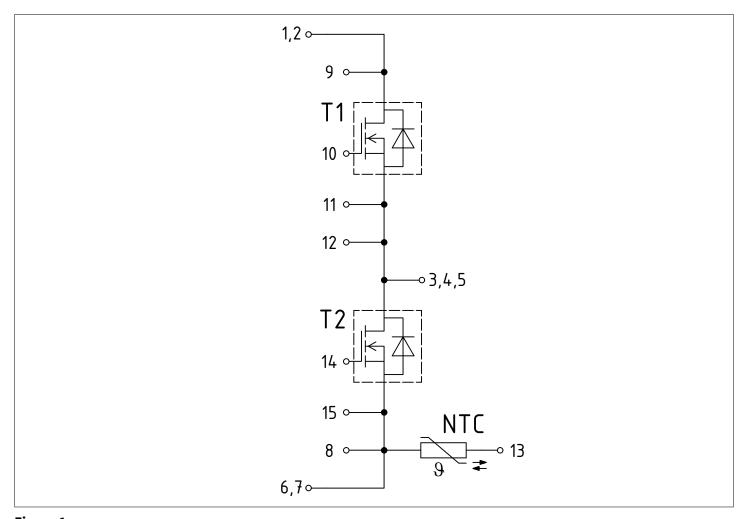
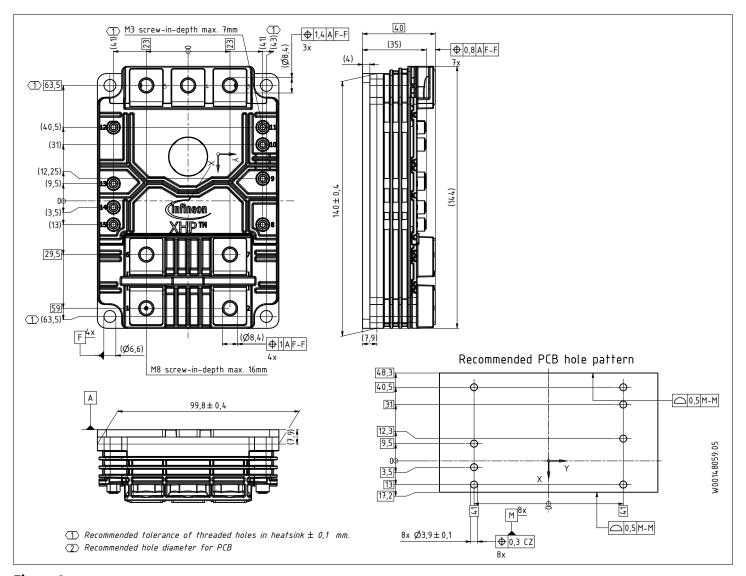


Figure 1

7 Package outlines



7 Package outlines



14

Figure 2

XHP™2 module

8 Module label code



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| Code format | Data Matrix | | Barcode 0 | Code128 |
|--------------|--|---|-----------|--|
| Encoding | ASCII text | | Code Set | A |
| Symbol size | 16x16 | | 23 digits | |
| Standard | IEC24720 and IEC16022 | | IEC8859-1 | |
| Code content | Content Module serial number Module material number Production order number Date code (production year) Date code (production week) | Digit 1 - 5 6 - 11 12 - 19 20 - 21 22 - 23 | | Example 71549 142846 55054991 15 30 |
| Example | 71549142846550549911530 | | | #6550549911530 |

Figure 3

XHP™2 module

Revision history



Revision history

| Document revision | Date of release | Description of changes |
|-------------------|-----------------|------------------------|
| 0.10 | 2025-06-02 | Preliminary datasheet |
| 1.00 | 2025-07-07 | Final datasheet |

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